

SMD Product handling manual (RECOMMENDED LAND PATTERN)

Note: This land pattern is not supported by the mounting evaluation.

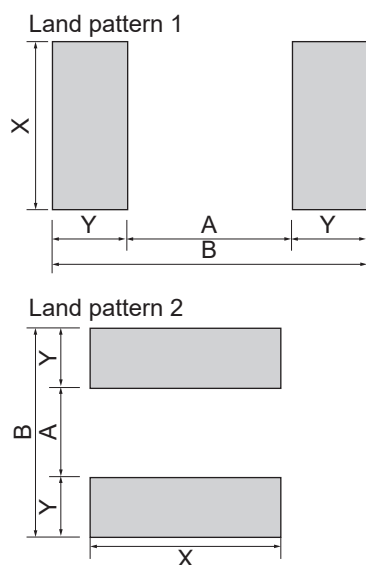
This is reference information only.

●Application

All KAMAYA Surface Mount Devices

●Recommended Land Pattern (Reference)

1. Square chip type (No. of terminals: 2)



Land pattern	Size		Flow soldering				Reflow soldering			
	Metric	Inch	A	B	X	Y	A	B	X	Y
1	0402	01005	Not applied				0.18	0.58	0.2	0.2
	0603	0201					0.3	0.9	0.3	0.3
	1005	0402					0.5	1.3	0.5	0.4
	1608	0603	1.0	2.6	0.8	0.8	1.0	2.0	0.8	0.5
	2012	0805	1.3	3.1	1.25	0.9	1.3	2.7	1.25	0.7
	3216	1206	2.2	4.3	1.6	1.05	2.2	3.9	1.6	0.85
	3225	1210	2.2	4.3	2.5	1.05	2.2	3.9	2.5	0.85
	5025	2010	3.9	6.3	2.5	1.2	3.9	5.9	2.5	1.0
	6332	2512	5.2	7.6	3.2	1.2	5.2	7.2	3.2	1.0
2	1632	0612	0.6	2.8	3.2	1.1	0.6	2.4	3.2	0.9
	2550	1020	1.3	3.8	5	1.25	1.3	3.4	5	1.05
	3263	1225	2.0	4.5	6.3	1.25	2.0	4.1	6.3	1.05

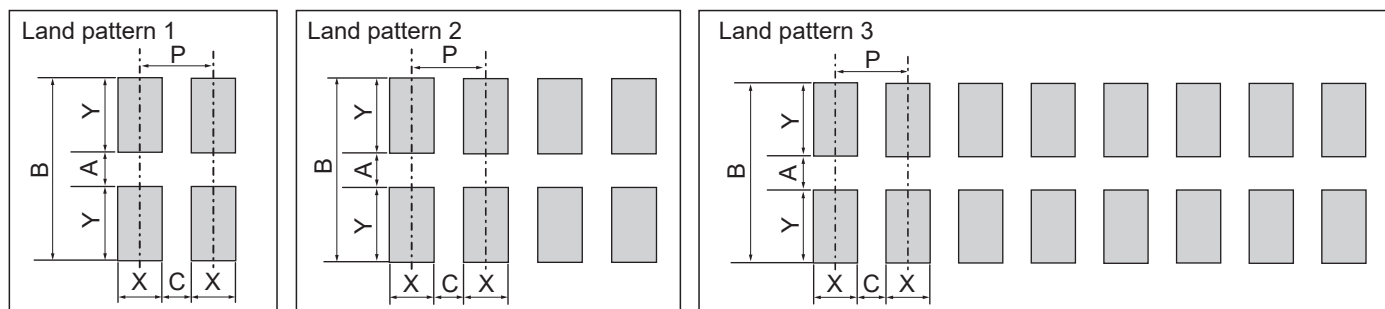
*For RLP and MLP, the recommended land pattern is set by resistance values.

Please look at corresponding page for further information.

Please contact Kamaya sales window for the recommended land pattern of WLP.

For RCC16, RCC20 and SPGA06, Please contact Kamaya sales dept.

2. Chip network type (No. of terminal: Multiple)



Land pattern	Style	Terminals style	P	Flow soldering					Reflow soldering				
				A	B	C	X	Y	A	B	C	X	Y
1	RAC062D	D	0.5	Not applied					0.3	0.9	0.2	0.3	0.3
1	RAC102D	C	0.65						0.5	1.3	0.34	0.33	0.4
	RAC101A		0.5						0.5	1.3	0.15	0.35	0.4
2	RAC104D, RACA104D		0.8	1.0	2.6	0.35	0.45	0.8	1.0	2.0	0.35	0.45	0.5
3	RAC168D		0.5	Not applied					1.0	2.0	0.2	0.3	0.5

●Others

(1) Please contact Kamaya sales dept for other products and further details.

(2) Please carry out an enough mounting evaluation when use these patterns.